

W6
B1
6 after polishing the metal layer, introducing a second agent comprising
hydrogen peroxide to a metal plug.

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1 9. (Twice amended) A method of removing at least one particle from a portion
2 of a metal layer on a substrate comprising:
depositing a slurry onto the substrate;
4 polishing the metal layer and the substrate; and
5 after polishing the metal layer, rinsing a metal plug with a solution
6 comprising hydrogen peroxide.

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1 14. (Twice amended) The method of claim 9, wherein polishing the metal layer
2 includes removing the metal layer at a rate of approximately in the range of
3 40Å/minute to 80Å/minute.

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1 18. (Twice amended) A method [of polishing a metal layer on a substrate]
2 comprising:
3 polishing the metal layer; and
4 after polishing the metal layer, introducing a rinsing solution onto a metal
5 plug, the rinsing solution comprising hydrogen peroxide.

1 19. (Twice amended) The method of claim 18, further including polishing the
2 metal layer with an abrasive material, wherein the rinsing solution is introduced
3 after [a] polishing of the substrate.